

Welcome to IEEE Xplore[®]

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

 Print FormatYour search matched **379** of **940663** documents.A maximum of **379** results are displayed, **50** to a page, sorted by **publication year** in **ascending** order.

You may refine your search by editing the current search expression or entering a new one the text box.

Then click **Search Again**.

(microprocessor* or "integrated circuit*") and "therm

[Search Again](#)**Results:**Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****1 VLSI Thermal Management in Cost Driven Systems***Lewis, T.; Adams, D.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 5 Issue: 4, Dec 1982

Page(s): 361 -367

[\[Abstract\]](#) [\[PDF Full-Text \(1544 KB\)\]](#) **IEEE JNL****2 Aluminum Nitride-An Alternative Ceramic Substrate for High Power Applications in Microcircuits***Werdecker, W.; Aldinger, F.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 7 Issue: 4, Dec 1984

Page(s): 399 -404

[\[Abstract\]](#) [\[PDF Full-Text \(1048 KB\)\]](#) **IEEE JNL****3 Thermal Characteristics of Plastic Small Outline Transistor (SOT) Packages***Alli, M.; Mahalingam, M.; Andrews, J.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 9 Issue: 4, Dec 1986

Page(s): 353 -363

[\[Abstract\]](#) [\[PDF Full-Text \(1720 KB\)\]](#) **IEEE JNL**

(microprocessor* or "integrated circuit*") and "thermal management"

4 Thermal Management of Air- and Liquid-Cooled Multichip Modules*Bar-Cohen, A.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 10 Issue: 2, Jun 1987

Page(s): 159 -175

[\[Abstract\]](#) [\[PDF Full-Text \(2704 KB\)\]](#) **IEEE JNL**

5 Advances in IC packaging, interconnect and assembly*Sage, M.;*

Electronic Manufacturing Technology Symposium, 1988, Fourth IEEE/CHMT European International, 13-15 Jun 1988

Page(s): 76 -79

[\[Abstract\]](#) [\[PDF Full-Text \(176 KB\)\]](#) **IEEE CNF**

6 Thermal advantages of a new microcircuit configuration*Pestorius, T.D.; Gregory, V.; Kraus, A.D.;*

Thermal Phenomena in the Fabrication and Operation of Electronic Components: I-THERM '88, InterSociety Conference on, 11-13 May 1988

Page(s): 33 -36

[\[Abstract\]](#) [\[PDF Full-Text \(256 KB\)\]](#) **IEEE CNF**

7 Thermal management of a high-performance multichip module*Chen, C.C.; Young, P.L.; Cech, J.M.;*

Electronics Components Conference, 1988., Proceedings of the 38th, 9-11 May 1988

Page(s): 302 -304

[\[Abstract\]](#) [\[PDF Full-Text \(1072 KB\)\]](#) **IEEE CNF**

8 Internal thermal resistance of a multi-chip packaging design for VLSI-based systems*Lee, Y.C.; Ghaffari, H.T.; Segelken, J.M.;*

Electronics Components Conference, 1988., Proceedings of the 38th, 9-11 May 1988

Page(s): 293 -301

[\[Abstract\]](#) [\[PDF Full-Text \(528 KB\)\]](#) **IEEE CNF**

9 Design of high-frequency hybrid power transformer*Gradzki, P.M.; Lee, F.C.;*

Applied Power Electronics Conference and Exposition, 1988. APEC '88. Conference Proceedings 1988., Third Annual IEEE, 1-5 Feb 1988

Page(s): 319 -326

[\[Abstract\]](#) [\[PDF Full-Text \(552 KB\)\]](#) **IEEE CNF**

10 An Addendum and Correction to "Thermal Management of Air- and Liquid-Cooled Multichip Modules"

Bar-Cohen, A.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 11 Issue: 3, Sep 1988

Page(s): 333 -334

[\[Abstract\]](#) [\[PDF Full-Text \(192 KB\)\]](#) **IEEE JNL**

11 Cooling techniques in electronics

Johnson, R.D.;

Thermal Design of Electronic Systems, IEE Colloquium on, 29 Mar 1989

Page(s): 5/1 -5/4

[\[Abstract\]](#) [\[PDF Full-Text \(140 KB\)\]](#) **IEEE CNF**

12 Quality issues of high pin count fine pitch VLSI packages

Hnatek, E.R.; Livesay, B.R.;

Test Conference, 1989. Proceedings. 'Meeting the Tests of Time'. , International, 29-31 Aug 1989

Page(s): 397 -421

[\[Abstract\]](#) [\[PDF Full-Text \(1372 KB\)\]](#) **IEEE CNF**

13 Packaging for a 1 Gb/s OEIC fiber-optic data link

Jackson, K.P.; Flint, E.B.; Cina, M.F.; Moll, A.J.; Ewen, J.F.; Flagello, D.; Rand, R.; Purushothaman, S.;

Electronic Components Conference, 1989. Proceedings., 39th, 22-24 May 1989

Page(s): 374 -377

[\[Abstract\]](#) [\[PDF Full-Text \(312 KB\)\]](#) **IEEE CNF**

14 3-D wafer-scale interconnect and packaging using photosensitive glass-ceramic substrates

Jacobi, W.J.; Reche, J.J.H.;

Aerospace and Electronics Conference, 1989. NAECON 1989., Proceedings of the IEEE 1989 National, 22-26 May 1989

Page(s): 4 -8 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(264 KB\)\]](#) **IEEE CNF**

15 Internal thermal resistance of a multi-chip packaging design for VLSI based systems

Lee, Y.C.; Ghaffari, H.T.; Segelken, J.M.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see

also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 12 Issue: 2 , Jun 1989
Page(s): 163 -169

[\[Abstract\]](#) [\[PDF Full-Text \(632 KB\)\]](#) **IEEE JNL**

16 INTELEC: Twelfth International Telecommunications Energy Conference (Cat. No.90CH2928-0)

Telecommunications Energy Conference, 1990. INTELEC '90., 12th International , 21-25 Oct 1990

[\[Abstract\]](#) [\[PDF Full-Text \(360 KB\)\]](#) **IEEE CNF**

17 Low T_g epoxy adhesives for thermal management

Chung, K.K.T.; Avery, E.; Boyle, A.; Dreier, G.; Koehn, W.; Govaert, G.; Theunissen, D.;

Electronic Manufacturing Technology Symposium, 1990, IEMT Conference., 8th IEEE/CHMT International , 7-9 May 1990

Page(s): 264 -277

[\[Abstract\]](#) [\[PDF Full-Text \(440 KB\)\]](#) **IEEE CNF**

18 Design of HWSI multichip modules for quick prototyping and manufacturing

Lee, Y.C.;

Electronic Components and Technology Conference, 1990. Proceedings., 40th , 20-23 May 1990

Page(s): 586 -591 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(388 KB\)\]](#) **IEEE CNF**

19 Development of robust hybrids for smart skin avionics

Thomas, T.L.;

Electronic Components and Technology Conference, 1990. Proceedings., 40th , 20-23 May 1990

Page(s): 131 -139 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(636 KB\)\]](#) **IEEE CNF**

20 Low temperature co-fired glass-ceramic, high-density-interconnect, substrate with improved thermal management

Rich, E.L., III; Martin, A.J.; Lengel, T.M.; Stewart, J.J.; Gallo, S.A.;

Electronic Components and Technology Conference, 1990. Proceedings., 40th , 20-23 May 1990

Page(s): 122 -130 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(688 KB\)\]](#) **IEEE CNF**

21 Silicon interconnect-a critical factor in device thermal management*Witzman, S.; Metelski, G.; Smith, K.;*

Thermal Phenomena in Electronic Systems, 1990. I-THERM II., InterSociety Conference on , 23-25 May 1990

Page(s): 154 -160

[\[Abstract\]](#) [\[PDF Full-Text \(756 KB\)\]](#) **IEEE CNF****22 Low temperature co-fired glass ceramic high density interconnect substrate with improved thermal management***Rich, E.L., III; Martin, A.J.; Lengel, T.M.; Stewart, J.J.; Gallo, S.A.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 13 Issue: 4 , Dec 1990

Page(s): 639 -646

[\[Abstract\]](#) [\[PDF Full-Text \(712 KB\)\]](#) **IEEE JNL****23 Silicon interconnect-a critical factor in device thermal management***Witzman, S.; Smith, K.; Metelski, G.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 13 Issue: 4 , Dec 1990

Page(s): 946 -952

[\[Abstract\]](#) [\[PDF Full-Text \(556 KB\)\]](#) **IEEE JNL****24 Hybrid technologies for high frequency switching power supplies***Belopolsky, Y.; Dassatti, R.;*

Electronic Components and Technology Conference, 1991. Proceedings., 41st , 11-16 May 1991

Page(s): 103 -108

[\[Abstract\]](#) [\[PDF Full-Text \(468 KB\)\]](#) **IEEE CNF****25 Factors in implementing MCM solutions for the high performance systems of the 1990s***Buschbom, M.L.; Calvin, S.E.;*

Custom Integrated Circuits Conference, 1991., Proceedings of the IEEE 1991 , 12-15 May 1991

Page(s): 27.1/1 -27.1/4

[\[Abstract\]](#) [\[PDF Full-Text \(308 KB\)\]](#) **IEEE CNF****26 GaAs HBTs: an analog circuit design perspective***Corcoran, J.; Poulton, K.; Knudsen, K.;*

Bipolar Circuits and Technology Meeting, 1991., Proceedings of the 1991 , 9-10 Sep 1991

Page(s): 245 -252

[\[Abstract\]](#) [\[PDF Full-Text \(712 KB\)\]](#) [IEEE CNF](#)

27 Hybrid packaging technique for high power density circuit

Ngon Binh Nguyen; Jones, F.B.;

Semiconductor Thermal Measurement and Management Symposium, 1991.

SEMI-THERM VII. Proceedings., Seventh Annual IEEE , 12-14 Feb 1991

Page(s): 105 -109

[\[Abstract\]](#) [\[PDF Full-Text \(212 KB\)\]](#) [IEEE CNF](#)

28 1991 Proceedings, Seventh Annual IEEE Semiconductor Thermal Measurement and Management Symposium (Cat. No.91CH2972-8)

Semiconductor Thermal Measurement and Management Symposium, 1991.

SEMI-THERM VII. Proceedings., Seventh Annual IEEE , 12-14 Feb 1991

[\[Abstract\]](#) [\[PDF Full-Text \(24 KB\)\]](#) [IEEE CNF](#)

29 Thermal modeling and analysis of pin grid arrays and multichip modules

Sullhan, R.; Fredholm, M.; Monaghan, T.; Agarwal, A.; Kozarek, B.;

Semiconductor Thermal Measurement and Management Symposium, 1991.

SEMI-THERM VII. Proceedings., Seventh Annual IEEE , 12-14 Feb 1991

Page(s): 110 -116

[\[Abstract\]](#) [\[PDF Full-Text \(520 KB\)\]](#) [IEEE CNF](#)

30 Eighth Annual IEEE Semiconductor Thermal Measurement and Management Symposium (Cat. No.92CH3095-7)

Semiconductor Thermal Measurement and Management Symposium, 1992.

SEMI-THERM VIII., Eighth Annual IEEE , 3-5 Feb 1992

[\[Abstract\]](#) [\[PDF Full-Text \(24 KB\)\]](#) [IEEE CNF](#)

31 The technology for over 300-pin QFPs

Shirai, Y.; Otsuka, K.; Okinaga, T.; Suzuki, H.; Murakami, G.; Arai, K.; Satuu, Y.; Emata, T.; Matsunaga, T.;

Electronic Components and Technology Conference, 1992. Proceedings., 42nd , 18-20 May 1992

Page(s): 423 -428

[\[Abstract\]](#) [\[PDF Full-Text \(420 KB\)\]](#) [IEEE CNF](#)

32 Multichip module enables for high reliability applications

Chu, D.; Reber, C.A.; Draper, B.L.; Sweet, J.N.; Palmer, D.W.;

Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE , 18-20 Mar 1992

Page(s): 102 -105

[\[Abstract\]](#) [\[PDF Full-Text \(328 KB\)\]](#) [IEEE CNF](#)

33 Thermal management for ceramic multichip modules: experimental program

Kromann, G.B.;

Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE , 18-20 Mar 1992

Page(s): 75 -78

[\[Abstract\]](#) [\[PDF Full-Text \(352 KB\)\]](#) [IEEE CNF](#)

34 Proceedings. 1992 IEEE Multi-Chip Module Conference MCMC-92 (Cat. No.92CH3124-5)

Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE , 18-20 Mar 1992

[\[Abstract\]](#) [\[PDF Full-Text \(36 KB\)\]](#) [IEEE CNF](#)

35 Wide band-gap semiconductor: how good is diamond?

Chalker, P.R.;

Diamond in Electronics and Optics, IEE Colloquium on , 4 Nov 1993

Page(s): 1/1 -1/3

[\[Abstract\]](#) [\[PDF Full-Text \(136 KB\)\]](#) [IEEE CNF](#)

36 Viking SuperSPARC AMCM development program

Eichelberger, C.W.; Davidson, H.;

Multi-Chip Module Conference, 1993. MCMC-93, Proceedings., 1993 IEEE , 15-18 Mar 1993

Page(s): 29 -32

[\[Abstract\]](#) [\[PDF Full-Text \(344 KB\)\]](#) [IEEE CNF](#)

37 High density overlay interconnect (HDI) delivers high frequency performance for GaAs systems

Gdula, M.; Haller, T.; Krishnamurthy, V.; Forman, G.;

Multi-Chip Module Conference, 1993. MCMC-93, Proceedings., 1993 IEEE , 15-18 Mar 1993

Page(s): 33 -38

[\[Abstract\]](#) [\[PDF Full-Text \(524 KB\)\]](#) [IEEE CNF](#)

38 The GE high density overlay MCM interconnect method solves high power needs of GaAs system design

Gdula, M.; Yerman, A.; Krishnamurthy, V.; Fillion, R.;

Wafer Scale Integration, 1993. Proceedings., Fifth Annual IEEE International Conference on , 20-22 Jan 1993

Page(s): 339 -345

[\[Abstract\]](#) [\[PDF Full-Text \(400 KB\)\]](#) **IEEE CNF**

39 Ninth Annual IEEE Semiconductor Thermal Measurement and Management Symposium (Cat. No.93CH3226-8)

Semiconductor Thermal Measurement and Management Symposium, 1993.
SEMI-THERM IX., Ninth Annual IEEE , 2-4 Feb 1993

[\[Abstract\]](#) [\[PDF Full-Text \(24 KB\)\]](#) **IEEE CNF**

40 Effect of molding compound thermal conductivity on thermal performance of molded multi-chip modules

Azar, K.; Mandrone, C.D.; Segelken, J.M.;

Semiconductor Thermal Measurement and Management Symposium, 1993.
SEMI-THERM IX., Ninth Annual IEEE , 2-4 Feb 1993

Page(s): 19 -27

[\[Abstract\]](#) [\[PDF Full-Text \(472 KB\)\]](#) **IEEE CNF**

41 Trends in low-cost, high-performance substrate technology

Carey, D.H.;

Micro, IEEE , Volume: 13 Issue: 2 , Apr 1993

Page(s): 19 -27

[\[Abstract\]](#) [\[PDF Full-Text \(776 KB\)\]](#) **IEEE JNL**

42 Addressing the challenges of advanced packaging and interconnection

Herrell, D.J.;

Micro, IEEE , Volume: 13 Issue: 2 , Apr 1993

Page(s): 10 -18

[\[Abstract\]](#) [\[PDF Full-Text \(808 KB\)\]](#) **IEEE JNL**

43 Electrical performance of flip-chip PBGA vs. CBGA

Sarfaraz, A.; Tai-Yu Chou; Omer, A.; Nealon, M.; Poehang Hsu; Khalili, S.;

Electrical Performance of Electronic packaging, 1994., IEEE 3rd Topical Meeting on , 2-4 Nov 1994

Page(s): 14 -17

[\[Abstract\]](#) [\[PDF Full-Text \(328 KB\)\]](#) **IEEE CNF**

44 Fabrication technology for wafer through-hole interconnections and three-dimensional stacks of chips and wafers

Linder, S.; Baltes, H.; Gnaedinger, F.; Doering, E.;

Micro Electro Mechanical Systems, 1994, MEMS '94, Proceedings, IEEE Workshop on , 1994

Page(s): 349 -354

[\[Abstract\]](#) [\[PDF Full-Text \(1028 KB\)\]](#) [IEEE CNF](#)

45 A hybrid-circuit tile-approach architecture for high-power spatial power-combined transmitters

Gouker, M.A.; Beaudette, R.G.; Delisle, J.T.;

Microwave Symposium Digest, 1994., IEEE MTT-S International , 23-27 May 1994

Page(s): 1545 -1548 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(446 KB\)\]](#) [IEEE CNF](#)

46 A hybrid-circuit tile-approach architecture for high-power spatial power-combined transmitters

Gouker, M.A.; Beaudette, R.G.; Delisle, J.T.;

Telesystems Conference, 1994. Conference Proceedings., 1994 IEEE National , 26-28 May 1994

Page(s): 47 -50

[\[Abstract\]](#) [\[PDF Full-Text \(360 KB\)\]](#) [IEEE CNF](#)

47 A study on the evaporation heat transfer in the cooling of high power electronics

Kristiansen, H.; Fallet, T.; Bjorneklett, A.;

Semiconductor Thermal Measurement and Management Symposium, 1994. SEMI-THERM X., Proceedings of 1994 IEEE/CPMT 10th , 1-3 Feb 1994

Page(s): 114 -120

[\[Abstract\]](#) [\[PDF Full-Text \(576 KB\)\]](#) [IEEE CNF](#)

48 Proceedings of 1994 IEEE/CHMT 10th Semiconductor Thermal Measurement and Management Symposium (SEMI-THERM)

Semiconductor Thermal Measurement and Management Symposium, 1994.

SEMI-THERM X., Proceedings of 1994 IEEE/CPMT 10th , 1-3 Feb 1994

[\[Abstract\]](#) [\[PDF Full-Text \(20 KB\)\]](#) [IEEE CNF](#)

49 A hi-density C4/CBGA interconnect technology for a CMOS microprocessor

Kromann, G.; Gerke, D.; Huang, W.;

Electronic Components and Technology Conference, 1994. Proceedings., 44th , 1-4 May 1994

Page(s): 22 -28

[\[Abstract\]](#) [\[PDF Full-Text \(628 KB\)\]](#) [IEEE CNF](#)

50 Thermal modeling and experimental characterization of the C4/surface-mount-array interconnect technologies

Kromann, G.B.;

Electronic Components and Technology Conference, 1994. Proceedings., 44th ,
1-4 May 1994
Page(s): 395 -402

[\[Abstract\]](#) [\[PDF Full-Text \(604 KB\)\]](#) **IEEE CNF**

[1](#) [2](#) [3](#) [4](#) [5](#) [6](#) [7](#) [8](#) [\[Next\]](#)

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#)
[Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#)
[No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2003 IEEE — All rights reserved